



NdelSV40-297IndraceSV40-297Indrach(This Join RealForm Factor(This Join RealOpenatorSV40-297Tarsfer ModeTurnster ModeTarsfer ModeSV10-200Capation ModeSV10-200Standard ModeNoSequential Real Performance (Ms/sec)Up SV20-200Sequential Acad Performance (Ms/sec)Up SV20-200Sequential Acad Performance (Ms/sec)SV20-200Sequential Comparator (Trict)SV20-200Standard Operating Temperator (Trict		
Connector (7+15) pin male Form Factor JEDEC MO-297 Operation Mode	Model	SV240-297
Form Factor JEDE MO-297 Operation Mode Transfer Mode Transfer Mode SD TLC Capacity 3D TLC Capacity 120GB - 960GB External DRAM NO Sequential Read Performance (MB/sec) Up to 560 Sequential Write Performance (MB/sec) Up to 520 ECC Engine Low-Density Parity-Check (LDPC) Code IOPS (4K Random Write) 85K Standard Operating Temperature (*C) 0 ~ +70 Extended Operating Temperature (*C) 40 ~ +85 Storage Temperature (*C) 50 reginal with ML-STD-202G) Vibration Operation Storage Temperature (*C) Storage Temperature (*C) Yes Storage Tempera	Interface	SATA 3.2 (6Gb/s)
Operation Mode Transfer Mode NAND Flash Type 3D TLC Capacity 120GB - 960GB External DRAM NO Sequential Read Performance (MB/sec) Up to 560 Sequential Write Performance (MB/sec) Up to 520 ECC Engine Low-Density Parity-Check (LDPC) Code IOPS (4K Random Write) 85K Standard Operating Temperature (°C) 0 ~ +70 Standard Operating Temperature (°C) 40 ~ +85 Storage Temperature (°C) 40 ~ +100 HW Write Protect Screw Hole Cable-Jess Solution Ves Storage Temperature (°C) Yes Stock Operation: 7.69 Grms, 20-200 Hz/random (Compliant with MLL STD-880S) (Compliant with MLL STD-880S) (Compliant with MLL STD-880S) Vibration Operation: 7.69 Grms, 55 - 2000 Hz/random (Compliant with MLL STD-880S) Operation: You Group Sol ± 5% Power Consumption Active mode: 30 mA / Idle mode: 100 mA Devers Consumption Sol ± 5%	Connector	(7+15) pin male
Tansfer Mode NAND Flash Type 3D TLC Capacity 120GB - 960GB External DRAM NO Sequential Read Performance (MB/sec) Up to 560 Sequential Witle Performance (MB/sec) Up to 520 ECC Engine Low-Density Parity-Check (LDPC) Code IOPS (4K Random Write) 85K Standard Operating Temperature (*C) 0 ~ +70 Standard Operating Temperature (*C) 40 ~ +85 Storage Temperature (*C) 40 ~ +85 Storage Temperature (*C) 40 ~ +85 Vibra Protect Storage Temperature (*C) Storage Temperature (*C) 40 ~ +85 Storage Temperature (*C) Yes Cable-less Solution Storage Temperature (*C) Thermal Sensor Yes Shock Compliant With ML*STD 202G) Non-operation: TS0 GMT 2050 NSSN (compliant With ML*STD 202G) Non-operat	Form Factor	JEDEC MO-297
NAND Flash Type 3D TLC Capacity 120GB - 960GB External DRAM NO Sequential Read Performance (MB/sec) Up to 560 Sequential Write Performance (MB/sec) Up to 520 ECC Engine Low-Density Parity-Check (LDPC) Code IOPS (4K Random Write) 85K Standard Operating Temperature (*C) -+70 Extended Operating Temperature (*C) -40 ~ +85 Storage Temperature (*C) -40 ~ +100 HW Write Protect - Storage Temperature (*C) -40 ~ +100 HW Write Protect - Storage Temperature (*C) -40 ~ +100 Storage Temperature (*C) -90 ~ +100 HW Write Protect - Storage Temperature (*C) -90 ~ +100 Storage Temperature (*C) Ves Storage Temperature (*C) -90 ~ +100 Storage Temperature (*C) -90 ~ 90 ~ 90 ~ 90 ~ 90 ~ 90 ~ 90 ~ 90 ~	Operation Mode	
Capacity 120GB - 960GB External DRAM NO Sequential Read Performance (MB/sec) Up to 560 Sequential Kead Performance (MB/sec) Up to 520 ECC Engine Low-Density Parity-Check (LDPC) Code IOPS (4K Random Write) 85K Standard Operating Temperature (*C) 0 ~ +70 Extended Operating Temperature (*C) 40 ~ +85 Storage Temperature (*C) 40 ~ +100 HVW Write Protect 500 Storage Temperature (*C) 40 ~ +100 HVW Write Protect 500 Storage Temperature (*C) 9 o = x100 Storage Temperature (*C) 40 ~ +100 HVW Write Protect 5000 Storage Temperature (*C) 40 ~ +100 Storage Temperature (*C) Yes Stock Operation: 50G/11ms (compliant with ML-STD-202G) (Non-Operation: 50G/15.05m) (compliant with ML-STD-202G) (Non-Operation: 400,000,000,000,000,000,000,000,000,000	Transfer Mode	
External DRAM NO Sequential Read Performance (MB/sec) Up to 560 Sequential Write Performance (MB/sec) Up to 520 ECC Engine Low-Density Parity-Check (LDPC) Code IOPS (4K Random Write) 85K Standard Operating Temperature (*C) 0 ~ +70 Extended Operating Temperature (*C) 40 ~ +85 Storage Temperature (*C) 40 ~ +100 Housing - H/W Write Protect - Screw Hole - Cable-less Solution Yes Shock Operation: 7.69 (Trans) Vibration Screm The Greme of the Greme of the Greme of the Green	NAND Flash Type	3D TLC
Sequential Read Performance (MB/sec)Up to 560Sequential Write Performance (MB/sec)Up to 520ECC EngineLow-Density Parity-Check (LDPC) CodeIOPS (4K Random Write)85KStandard Operating Temperature (*C)-40 ~ +85Storage Temperature (*C)-40 ~ +85Storage Temperature (*C)-40 ~ +100Housing-H/W Write Protect-Screw Hole-Cable-less SolutionYesShockOperation :SiG/11ms (compliant with ML_STD-202G) (compliant with ML_STD-202G) 	Capacity	120GB ~ 960GB
Sequential Write Performance (MB/sec) Up to 520 ECC Engine Low-Density Parity-Check (LDPC) Code IOPS (4K Random Write) 85K Standard Operating Temperature (*C) 0 ~ +70 Extended Operating Temperature (*C) -40 ~ +85 Storage Temperature (*C) -40 ~ +100 Housing - H/W Write Protect - Screw Hole - Cable-less Solution Yes Shock Compliant with MIL_STD-202G) Non-operation: 150G/11ms (compliant with MIL_STD-810G) Vibration Operation: 7.69 Grms, 20-2000 Hz/random (compliant with MIL_STD-810G) Operation: Voltage 5.0 V ± 5% Power Consumption Active mode: 530 mA / Idle mode: 100 mA Dimension (L x W x H) 54.0 x 39.8 x 4.0 mm	External DRAM	NO
ECC Engine Low-Density Parity-Check (LDPC) Code IOPS (4K Random Write) 85K Standard Operating Temperature (*C) 0 ~ +70 Extended Operating Temperature (*C) -40 ~ +85 Storage Temperature (*C) -40 ~ +100 Housing -40 ~ +100 H/W Write Protect - Screw Hole - Cable-less Solution Yes Shock Operation: 500/11ms (compliant with MLL-STD-202G) Non-operation: 500/20.5ms (compliant with MLL-STD-202G) Non-operation: 1500/20.5ms (compliant with MLL-STD-202G) Vibration Operation: 7.69 Grms, 20-2000 Hz/random (compliant with MLL-STD-803K) Vibration Operation: 7.69 Grms, 20-2000 Hz/random (compliant with MLL-STD-803K) Operation: Vibration Operation: 7.69 Grms, 20-2000 Hz/random (compliant with MLL-STD-803K) Operation: Vibration Operation: 7.69 Grms, 20-2000 Hz/random (compliant with ML-STD-801G) Non-operation: 4.02 Grms, 150-201G) Operating Voltage 5.0 V ± 5% Power Consumption Active mode: 530 mA / Idle mode: 100 mA Dimension (L x W x H) 54.0 x 39.8 x 4.0 mm	Sequential Read Performance (MB/sec)	Up to 560
IOPS (4K Random Write) 85K Standard Operating Temperature (°C) 0 ~ +70 Extended Operating Temperature (°C) -40 ~ +85 Storage Temperature (°C) -40 ~ +100 Housing - H/W Write Protect - Screw Hole - Cable-Jess Solution Yes Shock Operation: 50G/11ms (compliant with MIL-STD-202G) Non-operation: 1500G/0.5ms (compliant with MIL-STD-202G) Vibration Operation: 7.69 Grms, 20-2000 Hz/sine (compliant with MIL-STD-810G) Operating Voltage 5.0 V ± 5% Power Consumption Active mode: 530 mA / Idle mode: 100 mA Dimension (L x W x H) 54.0 x 39.8 x 4.0 mm	Sequential Write Performance (MB/sec)	Up to 520
Standard Operating Temperature (°C) 0 ~ +70 Extended Operating Temperature (°C) -40 ~ +85 Storage Temperature (°C) -40 ~ +100 Housing -40 ~ +100 H/W Write Protect - Screw Hole - Cable-less Solution Yes Shock Operation: 50G/11ms (compliant with ML-STD-202G) (Non-operation: 150G/0.5ms (compliant with ML-STD-833K) Vibration Operation: 7.69 Grms, 20-2000 Hz/random (compliant with ML-STD-810G) Vibration Operation: 7.69 Grms, 20-2000 Hz/random (compliant with ML-STD-810G) Operations Voltage 5.0 V ± 5% Power Consumption Active mode: 530 mA / Idle mode: 100 mA Dimension (L x W x H) 54.0 x 39.8 x 4.0 mm	ECC Engine	Low-Density Parity-Check (LDPC) Code
Extended Operating Temperature (°C)-40 ~ +85Storage Temperature (°C)-40 ~ +100Housing-40 ~ +100H/W Write Protect-40 ~ +100Screw Hole-40 ~ +100Cable-less Solution-40 ~ +100Thermal SensorYesShockOperation: SOG/11ms (compliant with MIL-STD-202G) Non-operation: 1500G/0.5ms (compliant with MIL-STD-203G) Non-operation: 1500G/0.5ms (compliant with MIL-STD-810G) Non-operation: 1500G/0.5ms (compliant with MIL-STD-810G) Non-operation: 100 MAOperating Voltage5.0 V ± 5%Power ConsumptionActive mode: 530 mA / Idle mode: 100 mADimension (L x W x H)54.0 x 38.8 x 4.0 mm	IOPS (4K Random Write)	85K
Storage Temperature (°C) -40 ~ +100 Housing -40 ~ +100 Housing -40 ~ +100 HW Write Protect	Standard Operating Temperature (°C)	0 ~ +70
Housing H/W Write Protect Screw Hole Cable-less Solution Thermal Sensor Yes Shock Operation: 50G/11ms (compliant with MIL-STD-202G) Non-operation: 150G/0.5ms (compliant with MIL-STD-803K) Vibration Operation: 7.69 Grms, 20-2000 Hz/random (compliant with MIL-STD-803K) Operation: 7.69 Grms, 20-2000 Hz/random (compliant with MIL-STD-803K) Operation: 7.69 Grms, 20-2000 Hz/random (compliant with MIL-STD-803K) Operation: 7.69 Grms, 20-2000 Hz/random (compliant with MIL-STD-810G) Operating Voltage 5.0 V ± 5% Power Consumption Active mode: 530 mA / Idle mode: 100 mA Dimension (L x W x H) 54.0 x 39.8 x 4.0 mm	Extended Operating Temperature (°C)	-40 ~ +85
H/W Write Protect Screw Hole Cable-less Solution Thermal Sensor Yes Shock Operation: SOG/11ms (compliant with MIL-STD-202G) Non-operation: 1500G/0.5ms (compliant with MIL-STD-202G) Vibration Operation: 7.69 Grms, 20~2000 Hz/random (compliant with MIL-STD-883K) Vibration Operation: 7.69 Grms, 20~2000 Hz/random (compliant with MIL-STD-810G) Operation: 0.50 Y± 5% Solution Power Consumption Active mode: 530 mA / Idle mode: 100 mA Dimension (L x W x H) 54.0 x 39.8 x 4.0 mm	Storage Temperature (°C)	-40 ~ +100
Screw Hole Cable-less Solution Thermal Sensor Yes Shock Operation: 50G/11ms (compliant with MIL-STD-202G) Non-operation: 1500G/0.5ms (compliant with MIL-STD-883K) Vibration Operation: 7.69 Grms, 20~2000 Hz/random (compliant with MIL-STD-803K) Operation: Voltage 5.0 V ± 5% Power Consumption Active mode: 530 mA / Idle mode: 100 mA Dimension (L x W x H) 54.0 x 39.8 x 4.0 mm	Housing	
Cable-less SolutionThermal SensorYesShockOperation: 50G/11ms (compliant with MIL-STD-202G) Non-operation: 1500G/0.5ms (compliant with MIL-STD-883K)VibrationOperation: 7.69 Grms, 20~2000 Hz/random (compliant with MIL-STD-810G) Non-operation: 4.02 Grms, 15 ~ 2000 Hz/sine (compliant with MIL-STD-810G)Operating Voltage5.0 V ± 5%Power ConsumptionActive mode: 530 mA / Idle mode: 100 mADimension (L x W x H)54.0 x 39.8 x 4.0 mm	H/W Write Protect	
Thermal SensorYesShockOperation: 50G/11ms (compliant with MIL-STD-202G) Non-operation: 1500G/0.5ms (compliant with MIL-STD-883K)VibrationOperation: 7.69 Grms, 20~2000 Hz/random (compliant with MIL-STD-810G) Non-operation: 4.02 Grms, 15~2000 Hz/sine (compliant with MIL-STD-810G)Operating Voltage5.0 V ± 5%Power ConsumptionActive mode: 530 mA / Idle mode: 100 mADimension (L x W x H)54.0 x 39.8 x 4.0 mm	Screw Hole	
ShockOperation: 50G/11ms (compliant with MIL-STD-202G) Non-operation: 1500G/0.5ms (compliant with MIL-STD-883K)VibrationOperation: 7.69 Grms, 20~2000 Hz/random (compliant with MIL-STD-810G) Non-operation: 4.02 Grms, 15 ~ 2000 Hz/sine (compliant with MIL-STD-810G)Operating Voltage5.0 V ± 5%Power ConsumptionActive mode: 530 mA / Idle mode: 100 mADimension (L x W x H)54.0 x 39.8 x 4.0 mm	Cable-less Solution	
(compliant with MIL-STD-202G) Non-operation: 1500G/0.5ms (compliant with MIL-STD-883K) Vibration Operation: 7.69 Grms, 20~2000 Hz/random (compliant with MIL-STD-810G) Non-operation: 4.02 Grms, 15 ~ 2000 Hz/sine (compliant with MIL-STD-810G) Operating Voltage 5.0 V ± 5% Power Consumption Active mode: 530 mA / Idle mode: 100 mA Dimension (L x W x H) 54.0 x 39.8 x 4.0 mm	Thermal Sensor	Yes
(compliant with MIL-STD-810G) Non-operation: 4.02 Grms, 15 ~ 2000 Hz/sine (compliant with MIL-STD-810G) Operating Voltage 5.0 V ± 5% Power Consumption Active mode: 530 mA / Idle mode: 100 mA Dimension (L x W x H) 54.0 x 39.8 x 4.0 mm	Shock	(compliant with MIL-STD-202G) Non-operation: 1500G/0.5ms
Power Consumption Active mode: 530 mA / Idle mode: 100 mA Dimension (L x W x H) 54.0 x 39.8 x 4.0 mm	Vibration	(compliant with MIL-STD-810G) Non-operation: 4.02 Grms. 15 ~ 2000 Hz/sine
Dimension (L x W x H) 54.0 x 39.8 x 4.0 mm	Operating Voltage	5.0 V ± 5%
	Power Consumption	Active mode: 530 mA / Idle mode: 100 mA
MTBF (hours) >3.000.000	Dimension (L x W x H)	54.0 x 39.8 x 4.0 mm
	MTBF (hours)	>3,000,000